

NPN Transistor Bare Die, MMBTA28

Darlington construction transistor in bare die form

Rev 1.0 26/11/24

Features:

- Collector current up to 0.8A
- Very high current gain
- Enables high impedance circuitry
- Gold back metal
- High reliability tested grades for Military + Space

Ordering Information:

The following part suffixes apply:

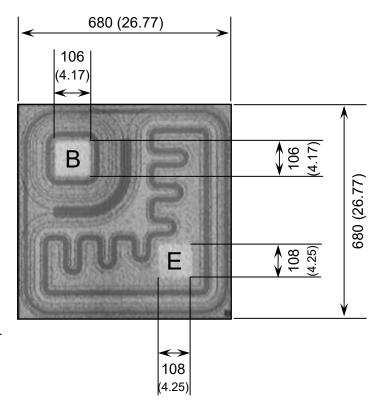
- No suffix Commercial grade die
- "H" Hi-rel grade die + MIL-STD-38534 Class H LAT
- "K" Hi-rel grade die + MIL-STD-38534 Class K LAT.

LAT = Lot acceptance Test.

For information on Hi-Rel LAT flows please see below.

www.siliconsupplies.com\bare-die-lot-qualification

Die Dimensions in µm (mils)



DIE BACK = COLLECTOR

Supply Formats:

- Default Die in Waffle Pack (400 per tray capacity)
- Sawn Wafer on Tape Specific request
- Unsawn Wafer Specific request
- With additional electrical selection Specific request
- Sawn as pairs or adjacent pair pick Specific request

Mechanical Specification

| Die Size (Excluding Saw Street) | 680 x 680 26.77 x 26.77 | μm mils | |
|------------------------------------|----------------------------|------------|--|
| Base Pad Size | 106 x 106 4.17 x 4.17 | µm mils | |
| Emitter Pad Size | 108 x 108 4.25 x 4.25 | µm mils | |
| Die Thickness | 230 (±20) 9.06 (±0.79) | μm mils | |
| Top Metal Composition | Al - 2μm | | |
| Back Metal Composition | AuAs - 0.9μm | | |
| | | | |





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Rev 1.0 07/07/17

Absolute Maximum Ratings T_A = 25°C unless otherwise stated

| PARAMETER | SYMBOL | VALUE | UNIT |
|---------------------------|------------------|------------|------|
| Collector-Base Voltage | V _{CBO} | 80 | V |
| Collector-Emitter Voltage | V _{CEO} | 80 | V |
| Emitter-Base Voltage | V _{EBO} | 12 | V |
| Collector Current | Ic | 800 | mA |
| Junction Temperature | TJ | 150 | °C |
| Storage Temperature | T _{stg} | -55 to 150 | °C |

Electrical Characteristics T_A = 25°C unless otherwise stated

| PARAMETER | SYMBOL | CONDITIONS | MIN | TYP | MAX | UNIT | |
|---|----------------------|---|-------|-----|-----|------|--|
| OFF CHARACTERISTICS | | | | | | | |
| Collector-Base Breakdown Voltage | V _{(BR)CBO} | $I_C = 100 \mu A, I_E = 0$ | 80 | - | - | V | |
| Collector-Emitter Breakdown Voltage | V _{(BR)CEO} | $I_C = 100 \mu A, I_B = 0$ | 80 | - | - | V | |
| Emitter-Base Breakdown Voltage | V _{(BR)EBO} | $I_E = 10 \mu A, I_C = 0$ | 12 | - | - | V | |
| Collector Cut-off Current | I _{CBO} | $V_{CB} = 60V, I_{E} = 0$ | - | - | 100 | nA | |
| | I _{CES} | V _{CE} = 60V, I _E = 0 | - | - | 500 | nA | |
| Emitter Cut-off Current | I _{EBO} | V _{EB} = 10V, I _C = 0 | - | - | 100 | nA | |
| ON CHARACTERISTICS ¹ | | | | | | | |
| Forward-Current Transfer Ratio | h _{FE} | V _{CE} = 5V, I _C = 10mA | 10000 | - | - | - | |
| | | $V_{CE} = 5V, I_{C} = 100mA$ | 10000 | - | - | - | |
| Collector-Emitter Saturation Voltage | V _{CE(sat)} | $I_C = 10 \text{mA}, I_B = 0.01 \text{mA}$ | - | - | 1.2 | V | |
| | | $I_C = 100 \text{mA}, I_B = 0.1 \text{mA}$ | - | - | 1.5 | V | |
| Base-Emitter On Voltage | V _{BE(on)} | I _C = 100mA, V _{CE} = 5V | - | - | 2.0 | V | |
| SMALL SIGNAL CHARACTERISTICS ² | | | | | | | |
| Transition Frequency | f⊤ | I _C = 15mA, V _{CE} = 5V, f = 100MHz | 125 | - | - | MHz | |
| Output Capacitance | C _{obo} | V _{CB} = 10V, I _E = 0, f = 1MHz | - | - | 8 | pF | |

^{1.} Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2% 2. Not production testing in die form, characterized by chip design and tested in package

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